

Title (en)
COPPER ALLOY AND COPPER ALLOY THIN SHEET EXHIBITING IMPROVED WEAR OF BLANKING METAL MOLD

Title (de)
KUPFER-LEGIERUNG UND DARAUS BESTEHENDES DÜNNES BLECH MIT VERBESSERTEM VERSCHLEISS FÜR EINE ROHUMFORM-KOKILLE

Title (fr)
ALLIAGE DE CUIVRE ET FEUILLE MINCE EN ALLIAGE DE CUIVRE POSSEDANT UNE RESISTANCE A L'USURE AMELIOREE EN TANT QUE MOULE METALLIQUE D'ESTAMPAGE

Publication
EP 0995808 A4 20060412 (EN)

Appication
EP 99939202 A 19990309

Priority

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- JP 4432299 A 19990223

Abstract (en)
[origin: EP0995808A1] A copper-based alloy having excellent blanking die wear resistance, repeated bending fatigue resistance, and solderability as well as excellent resin adhesion, comprising 1.5 to 2.4 weight % of Fe, 0.008 to 0.08 weight % of P, 0.01 to 0.50 weight % of Zn, and 0.0005 to 0.02 weight % of C, and, if required, further containing 0.003 to 0.5 weight % of Ni and 0.003 to 0.5 weight % of Sn, and further containing a total amount of 0.0007 to 0.5 weight % of one or two or more elements selected from the group consisting of Al, Be, Ca, Cr, Mg and Si, and the balance being Cu and inevitable impurities, in which the total content of one or two or more elements selected from the group consisting of Nb, Ti, Zr, Ta, Hf, W, V and Mo is limited to less than 0.01 weight %.

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IPC 8 full level
C22C 9/00 (2006.01); **C22C 9/04** (2006.01); **C22C 9/06** (2006.01); **C22C 9/10** (2006.01)

CPC (source: EP KR)
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